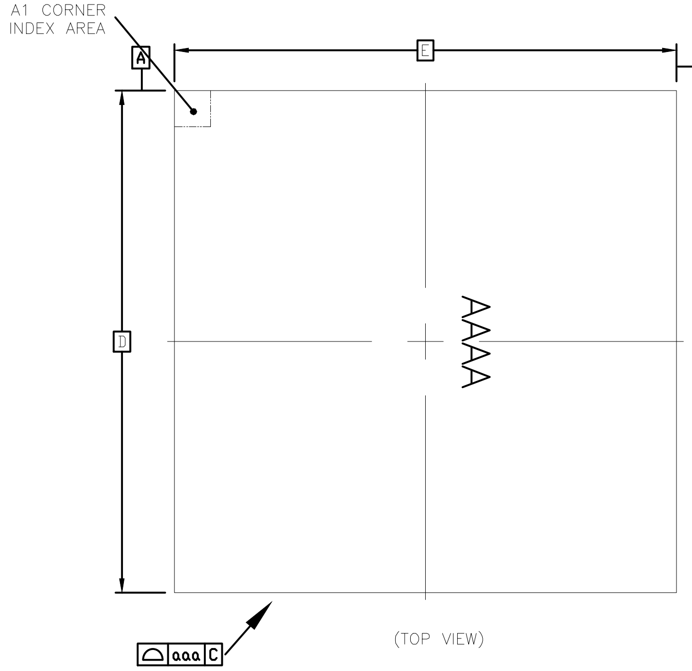
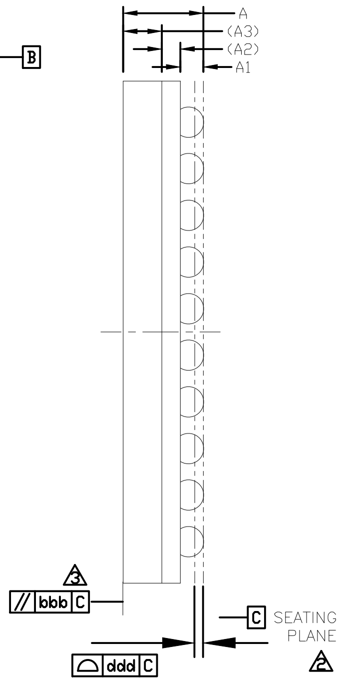
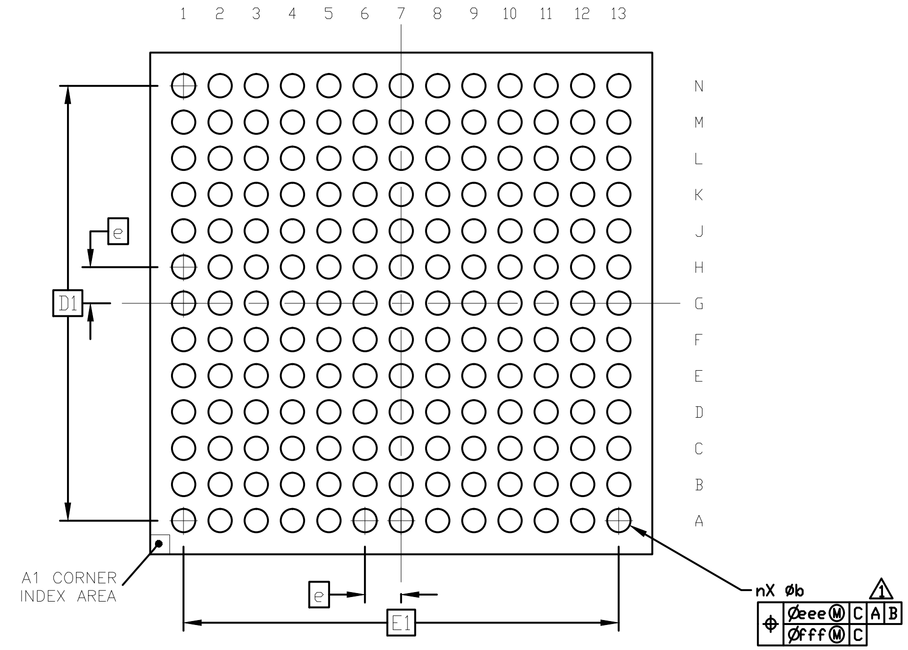


(TOP VIEW)





(BOTTOM VIEW)

-DRAWING NOT TO SCALE-

	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOR.	MAX.
TOTAL THICKNESS	A	---	---	1.2
STAND OFF	A1	0.27	---	0.37
SUBSTRATE THICKNESS	A2		0.26	REF
MOLD THICKNESS	A3		0.54	REF
BODY SIZE	D		9	BSC
	E		9	BSC
BALL DIAMETER			0.4	
BALL OPENING			0.3	
BALL WIDTH	b	0.37	---	0.47
BALL PITCH	e		0.65	BSC
BALL COUNT	n		169	
EDGE BALL CENTER TO CENTER	D1		7.8	BSC
	E1		7.8	BSC
BODY CENTER TO CONTACT BALL	SD		---	BSC
	SE		---	BSC
PACKAGE EDGE TOLERANCE	aaa		0.1	
MOLD FLATNESS	bbb		0.2	
COPLANARITY	ddd		0.12	
BALL OFFSET (PACKAGE)	eee		0.15	
BALL OFFSET (BALL)	fff		0.08	

NOTES:

1. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE C.
2. DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
3. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
4. PACKAGE CODE: X16999+1, X16999+2C

maxim
integrated™

TITLE:
PACKAGE OUTLINE, 169 BALLS CTBGA
9X9X1.2 mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
WENJIA SONG	21-100423	B	1/1